Appl. No. 10/613,254 Examiner: Garcia, Joannie A, Art Unit 2823

In response to the Office Action dated January 21, 2004

Date: April 5, 2004 Attorney Docket No. 10112381

## **AMENDMENTS TO THE SPECIFICATION**

Please replace the paragraph at page 7, line 16 with the following rewritten paragraph.

Referring to FIG. 1H, an etching process forming an M0 landing pad and local interconnection is performed to form an M0 landing pad and local interconnection recesses 132 in the insulating layer [[134]] 124, thereby defining a landing pad pattern and a local interconnection pattern.